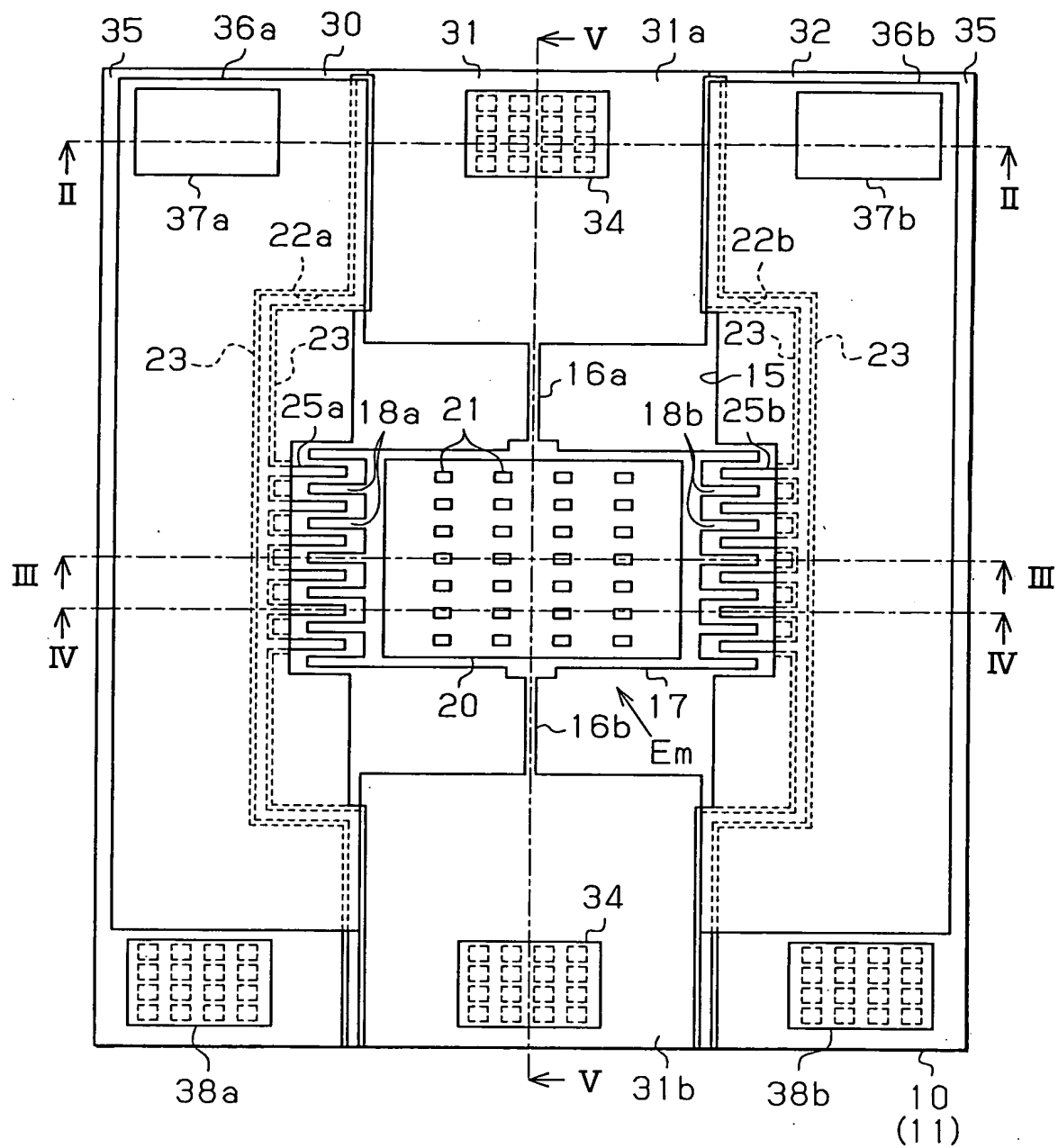
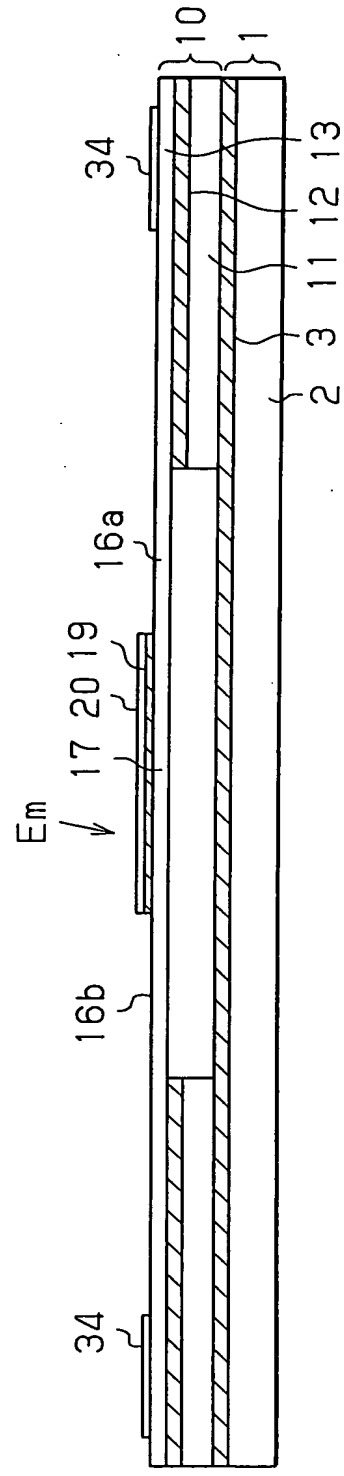


FIG. 1

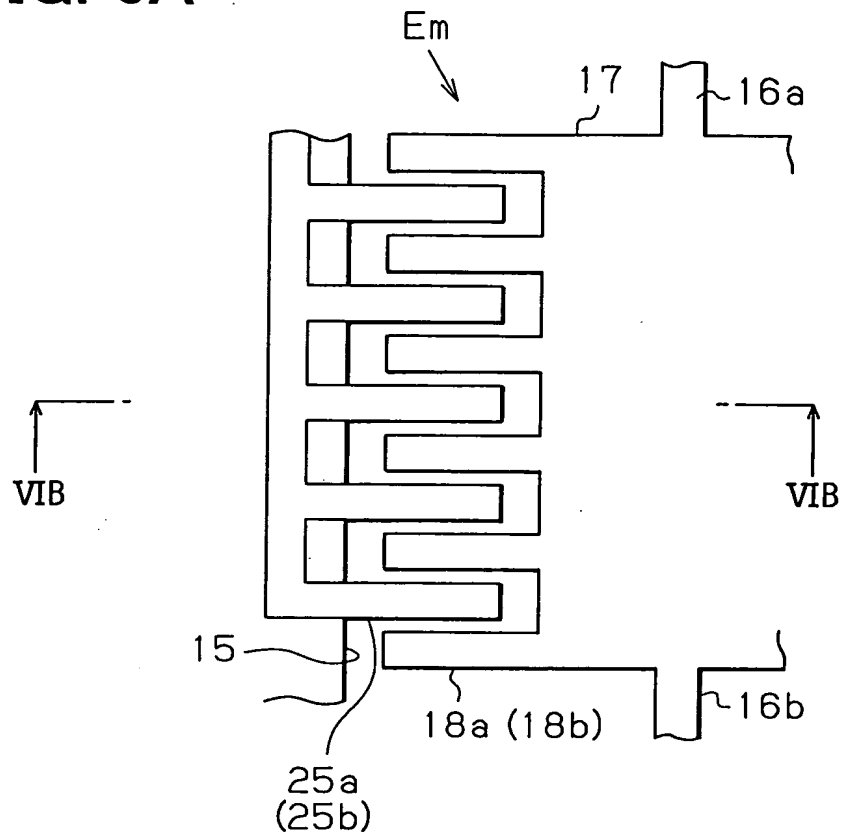


[illegible]

FIG. 5



**FIG. 6A**



**FIG. 6B**

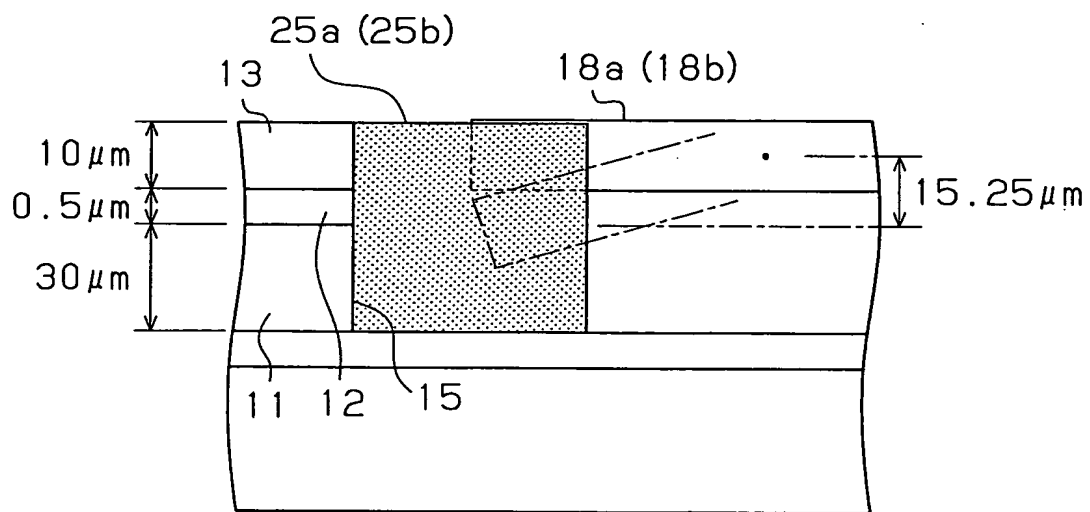


FIG. 7A

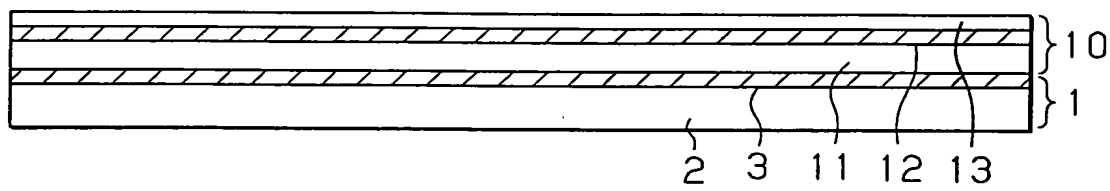


FIG. 7B

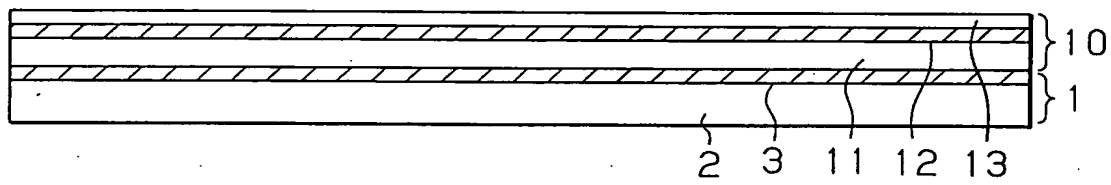
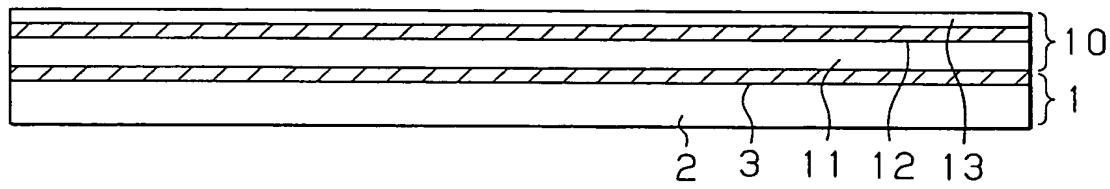
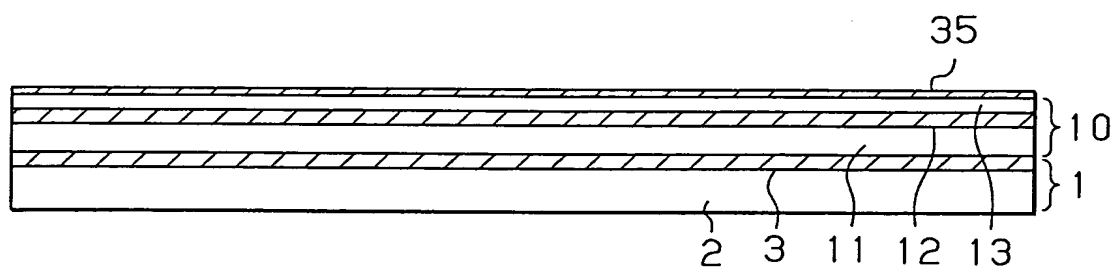


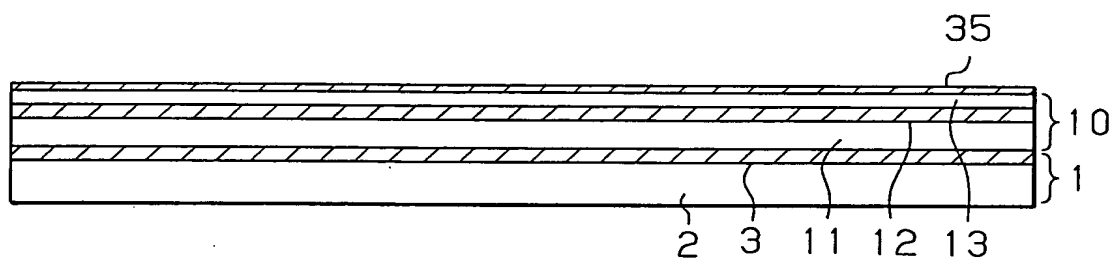
FIG. 7C



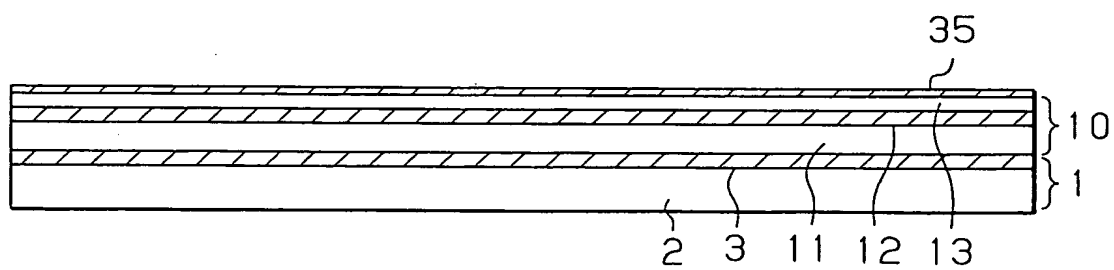
**FIG. 8A**



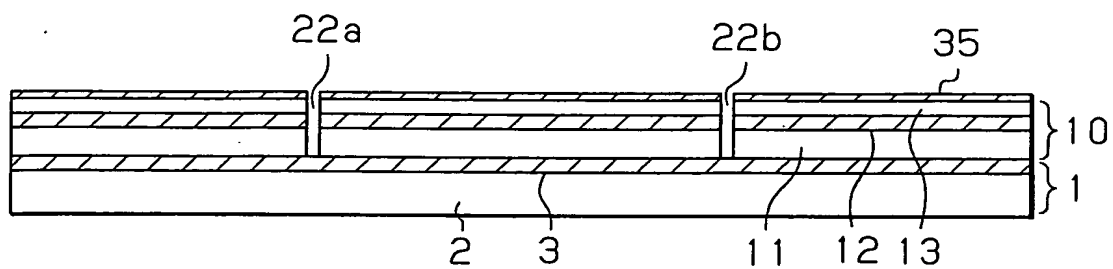
**FIG. 8B**



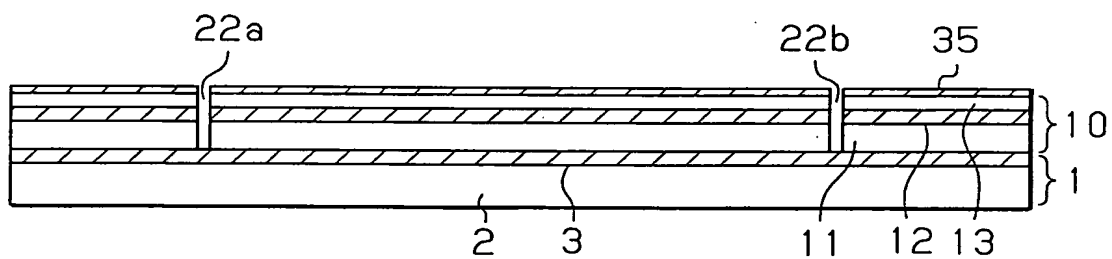
**FIG. 8C**



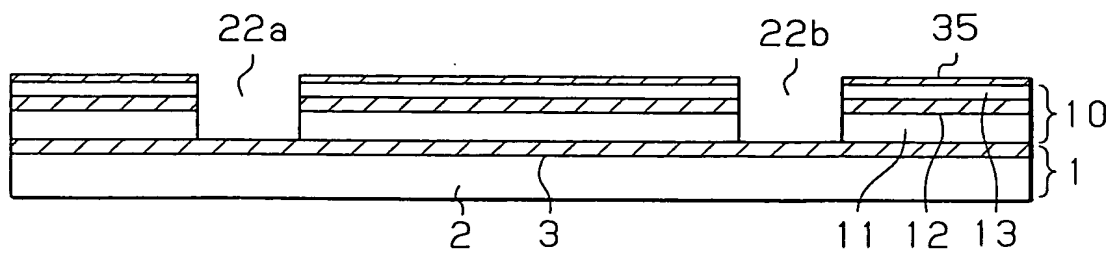
**FIG. 9A**



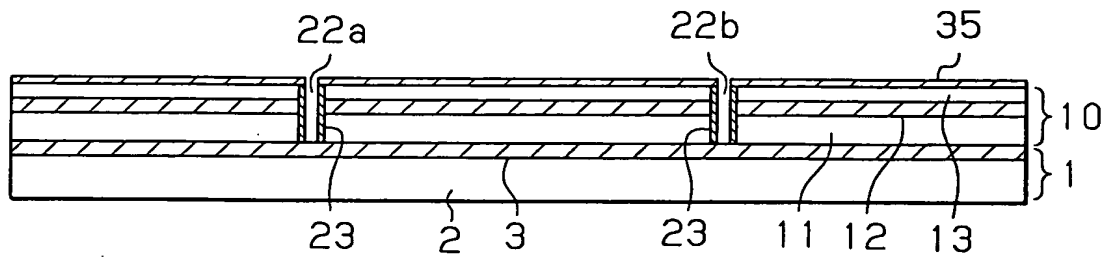
**FIG. 9B**



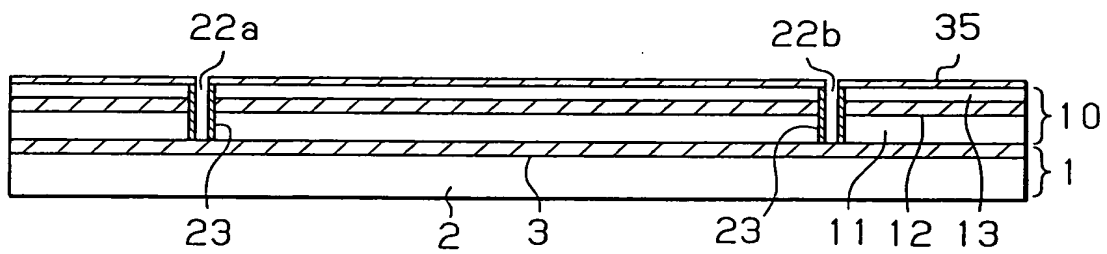
**FIG. 9C**



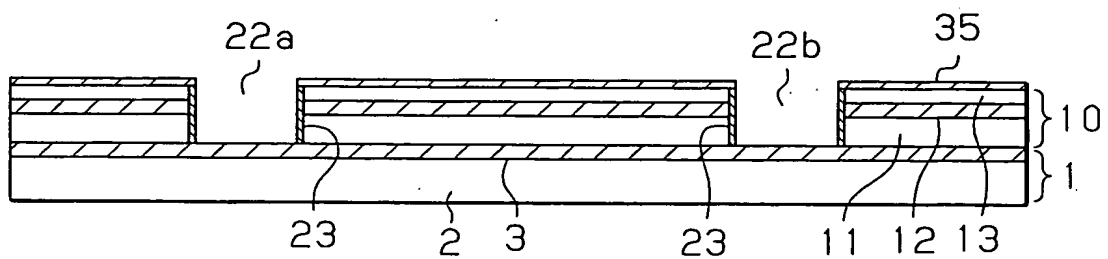
**FIG. 10A**



**FIG. 10B**

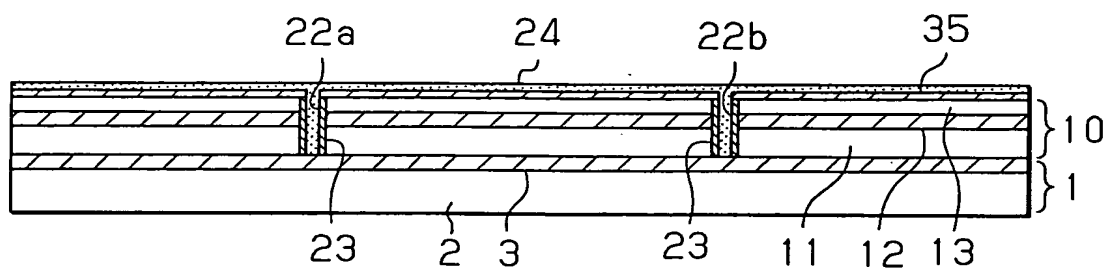


**FIG. 10C**

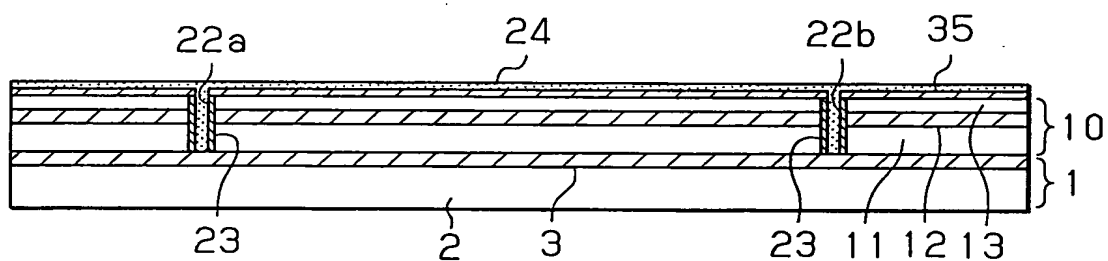




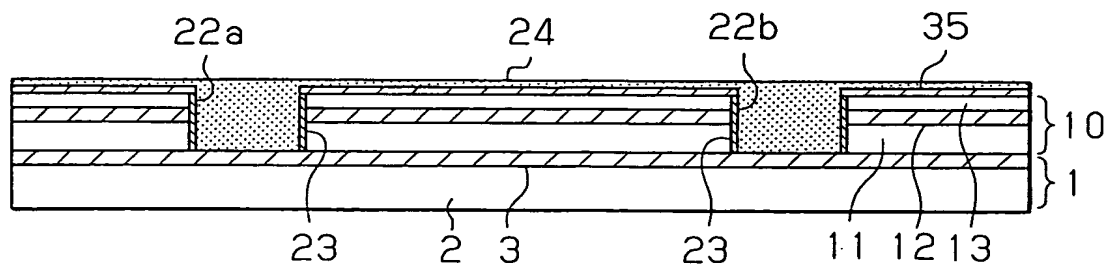
**FIG. 12A**



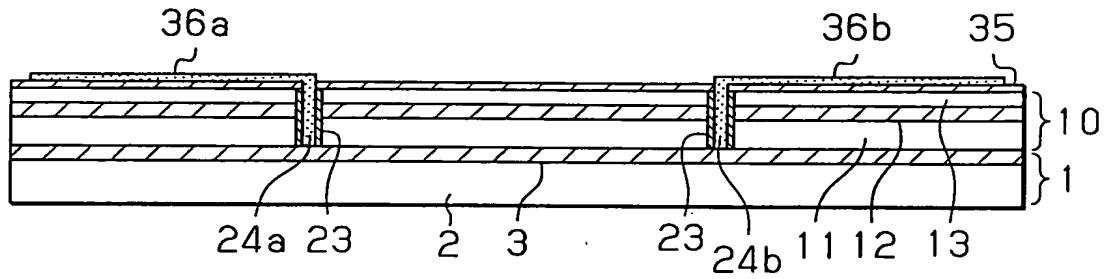
**FIG. 12B**



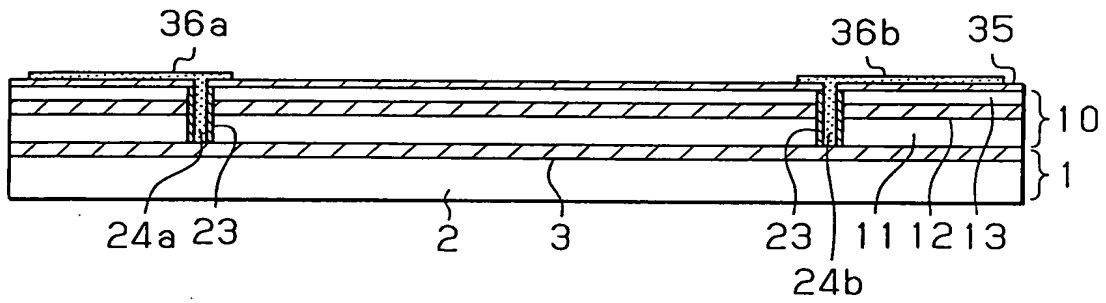
**FIG. 12C**



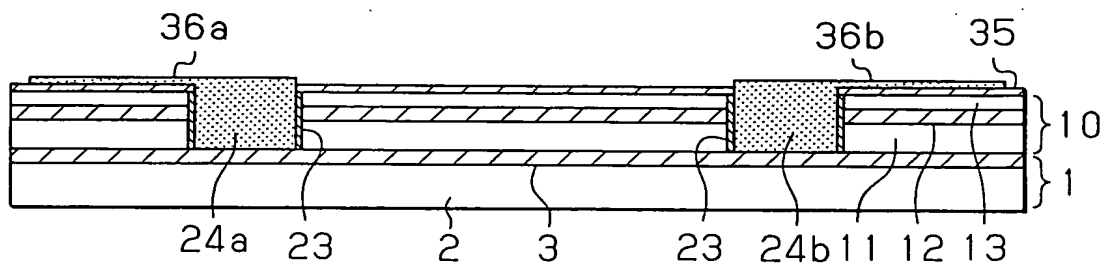
**FIG. 13A**



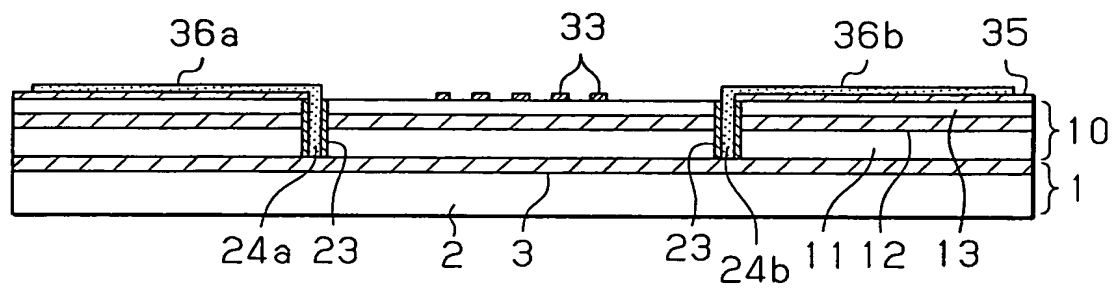
**FIG. 13B**



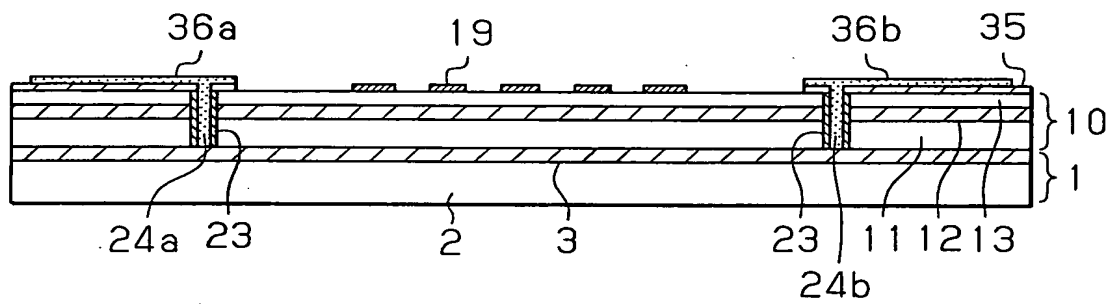
**FIG. 13C**



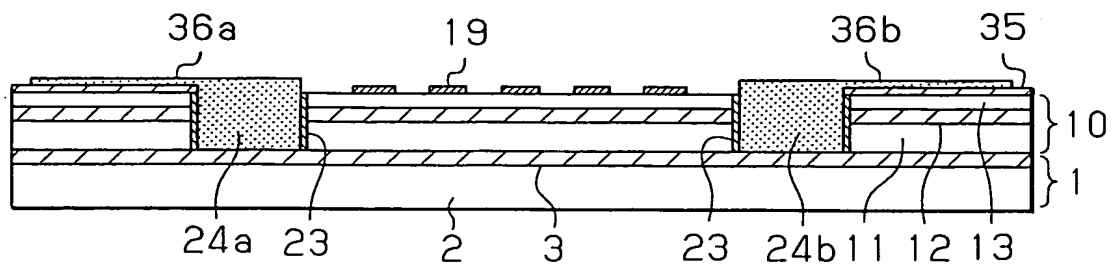
**FIG. 14A**



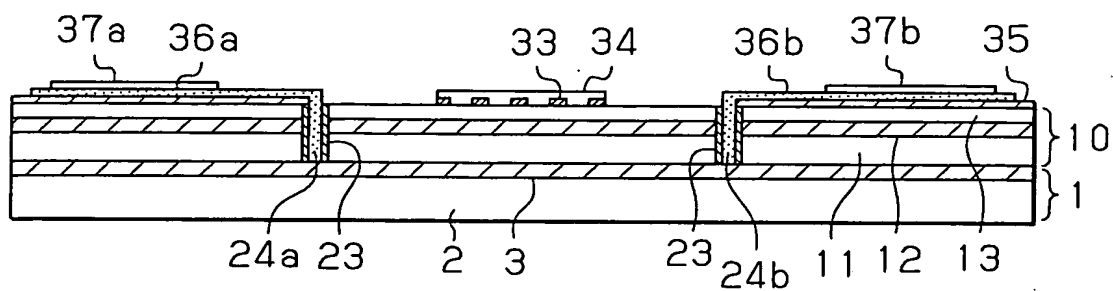
**FIG. 14B**



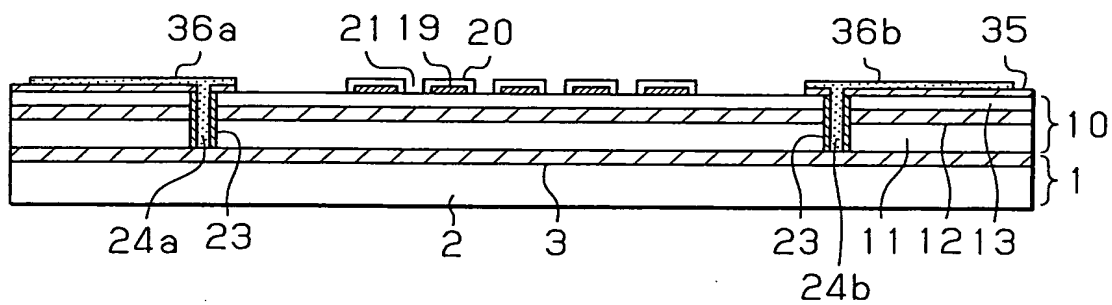
**FIG. 14C**



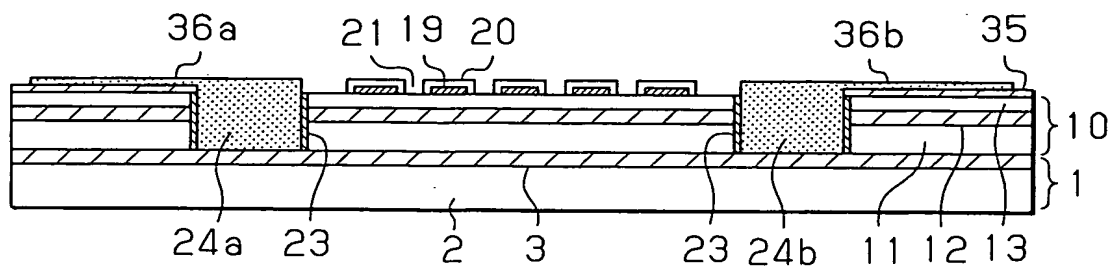
**FIG. 15A**



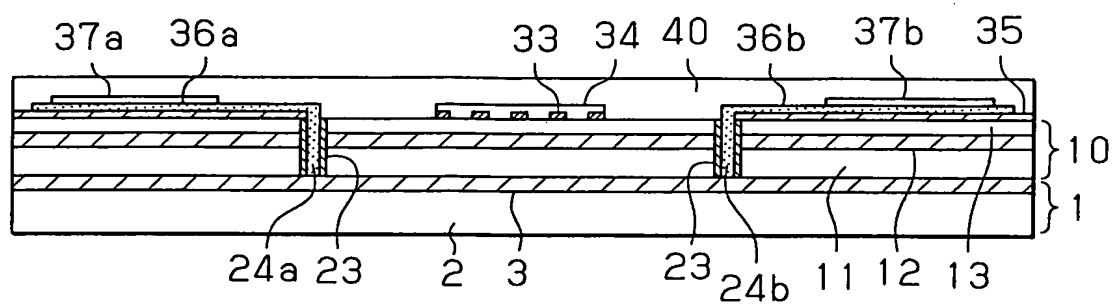
**FIG. 15B**



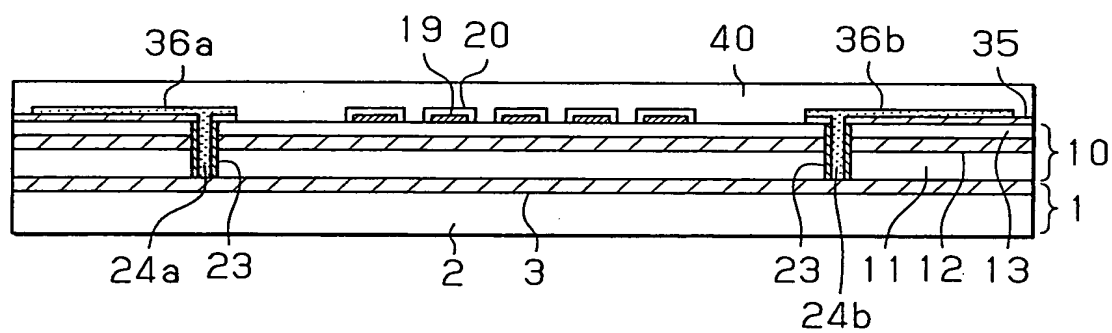
**FIG. 15C**



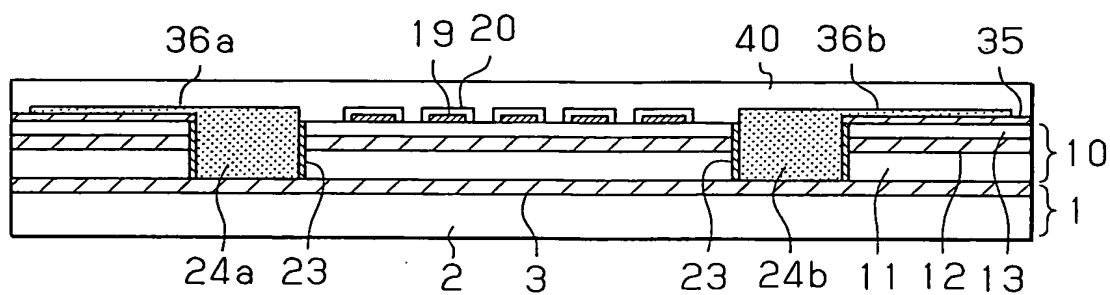
**FIG. 16A**



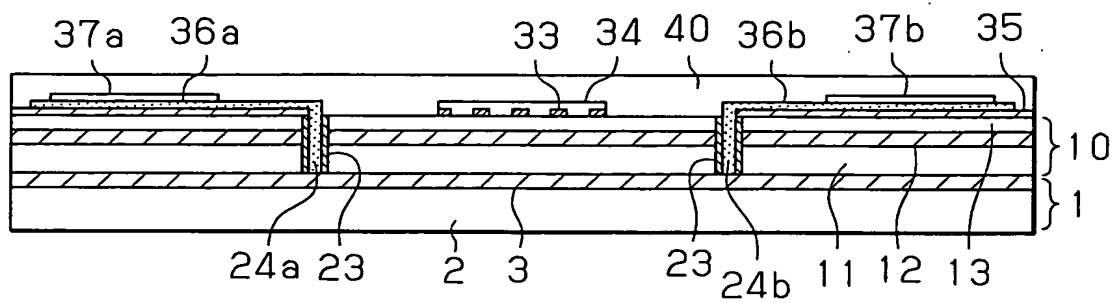
**FIG. 16B**



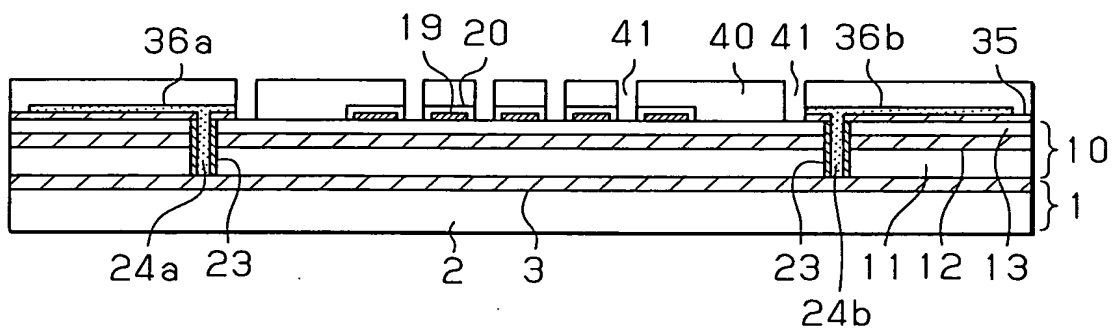
**FIG. 16C**



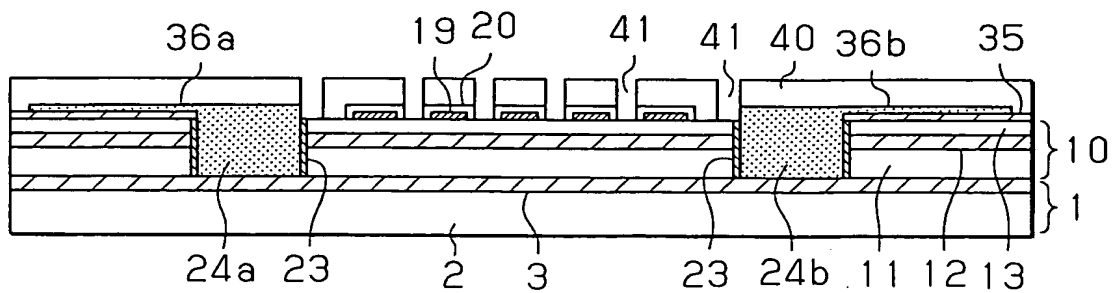
**FIG. 17A**



**FIG. 17B**



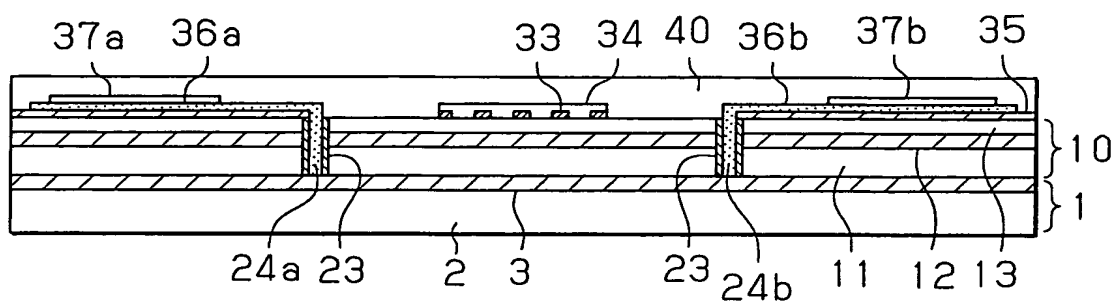
**FIG. 17C**



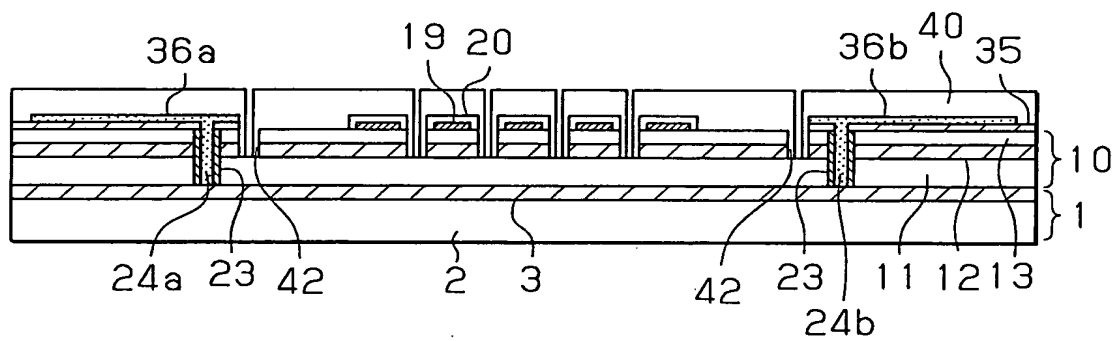
[illegible][illegible]

FIG. 1 is a cross-sectional view of a semiconductor device. The device is formed on a substrate 1. A base layer 2 is provided on the substrate. On the base layer, there are several layers: a first layer 3, a second layer 15, and a third layer 20. The device is divided into two main sections, 36a and 36b, which are separated by a central region 40. The sections 36a and 36b are further divided into sub-sections 24a and 24b. The central region 40 is divided into sub-sections 21 and 19. The device is also labeled with 10 and 11.

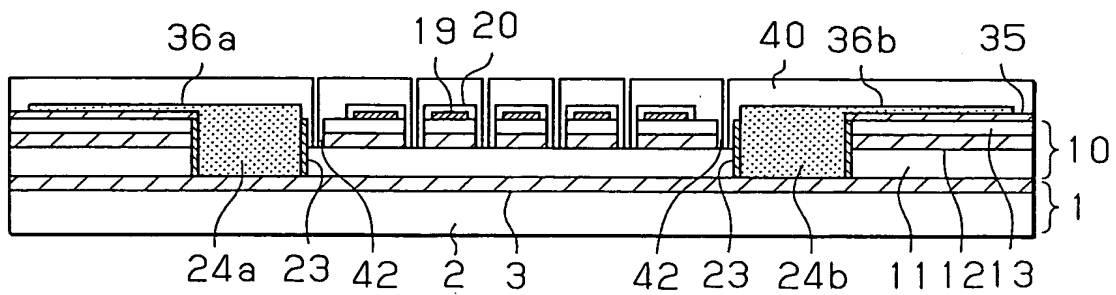
# FIG. 19A



# FIG. 19B



# FIG. 19C



**FIG. 20A**

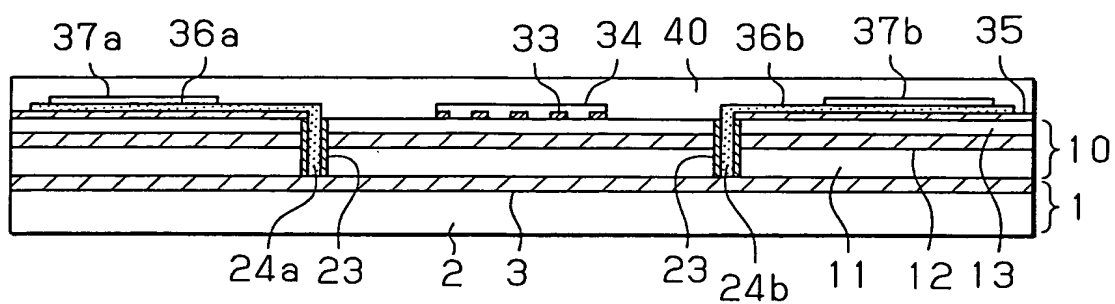
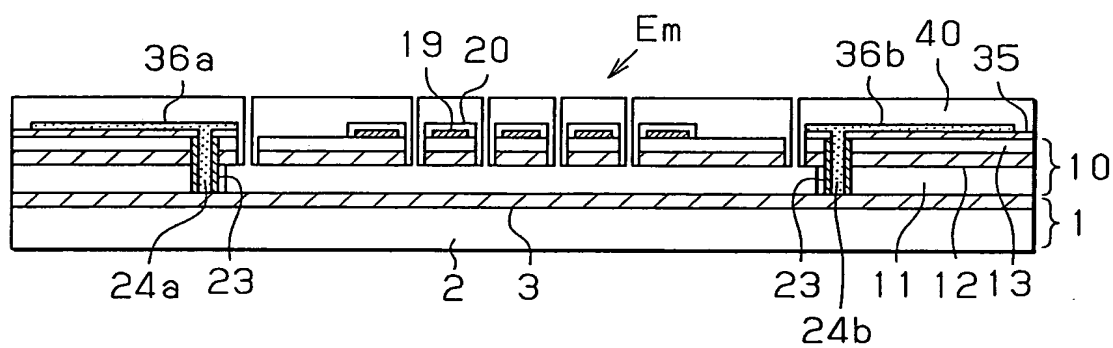
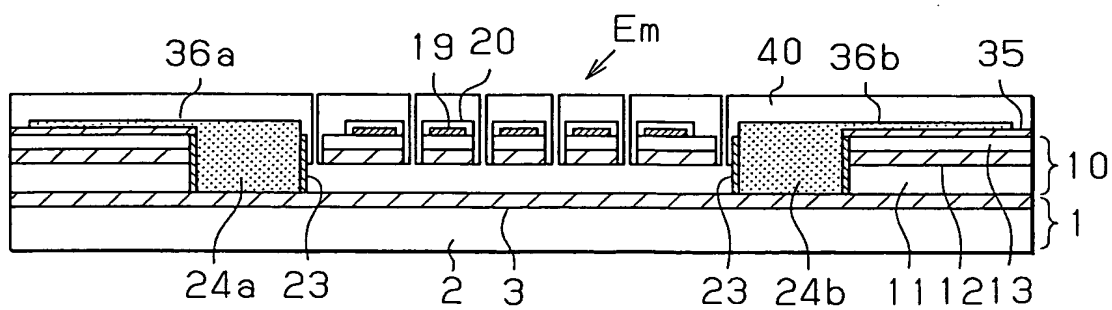


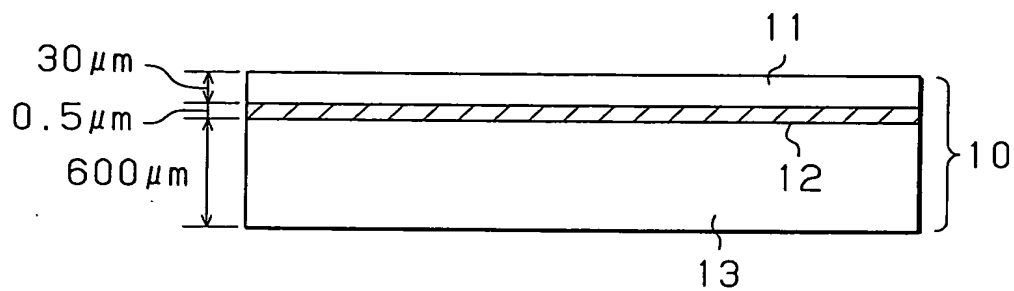
FIG. 20B



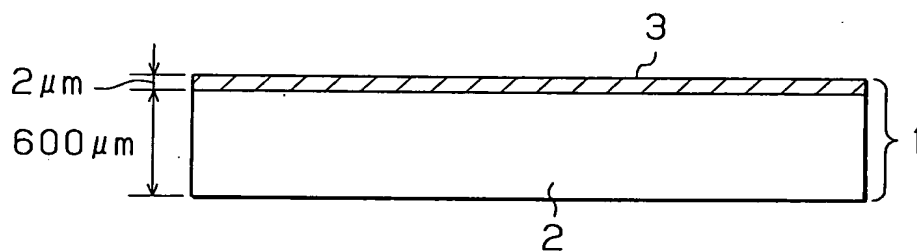
**FIG. 20C**



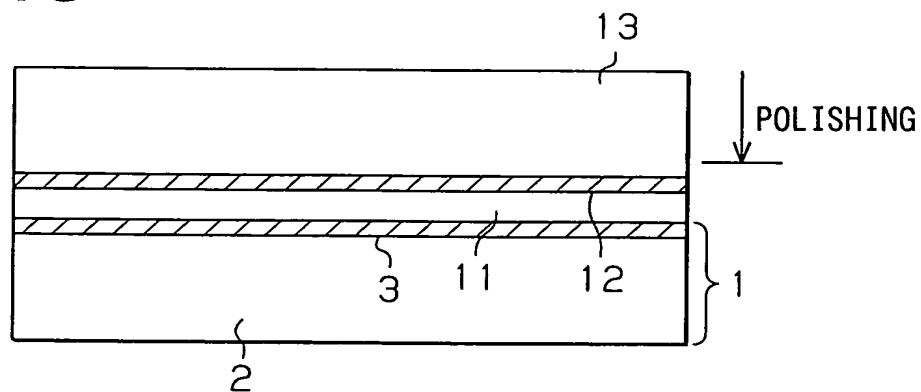
**FIG. 21A**



**FIG. 21B**



**FIG. 21C**



**FIG. 21D**

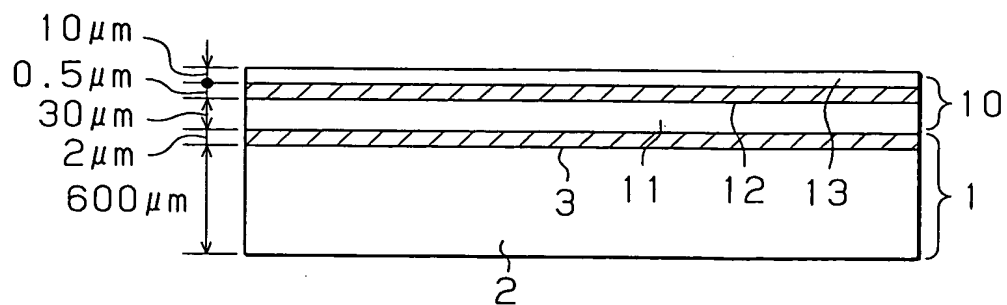


FIG. 22A

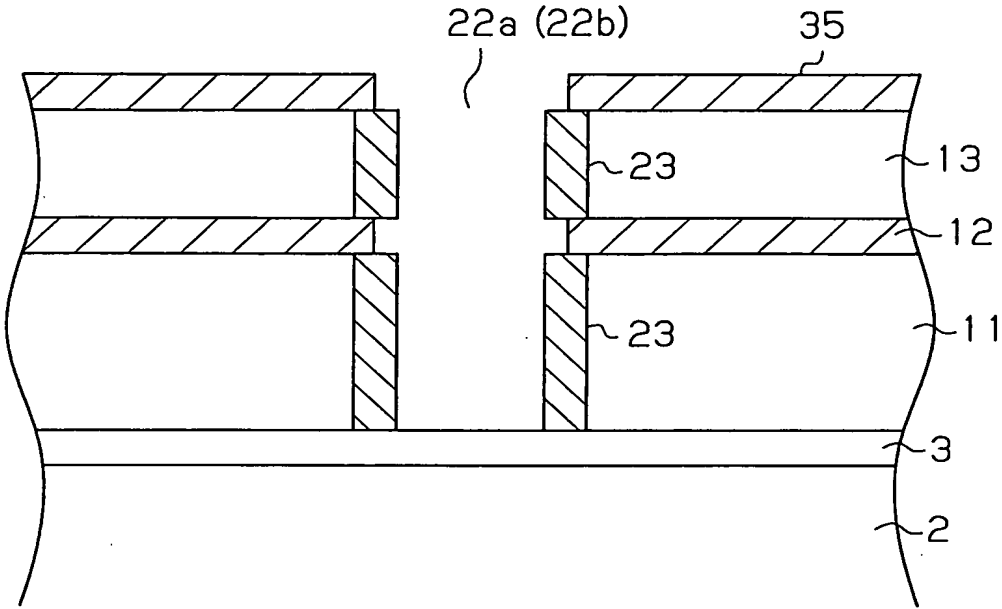


FIG. 22B

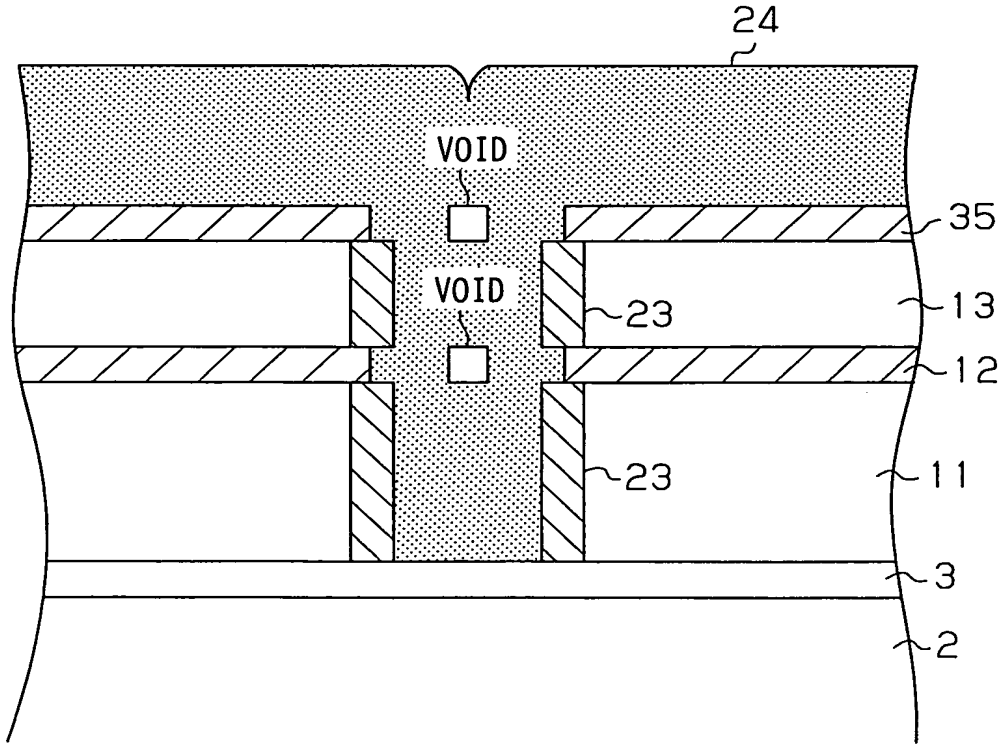


FIG. 23

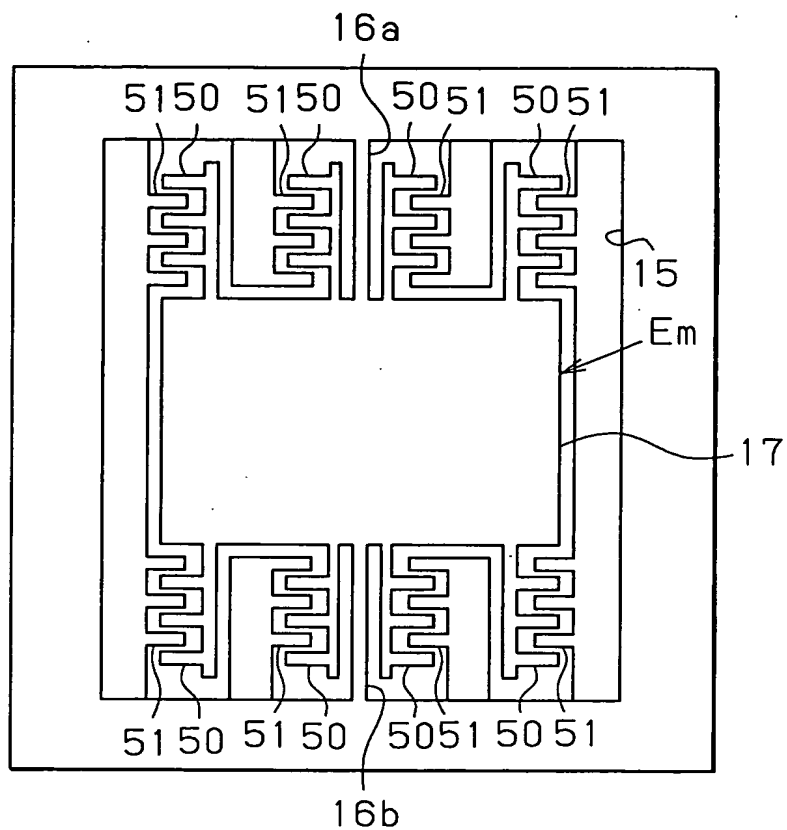


FIG. 24

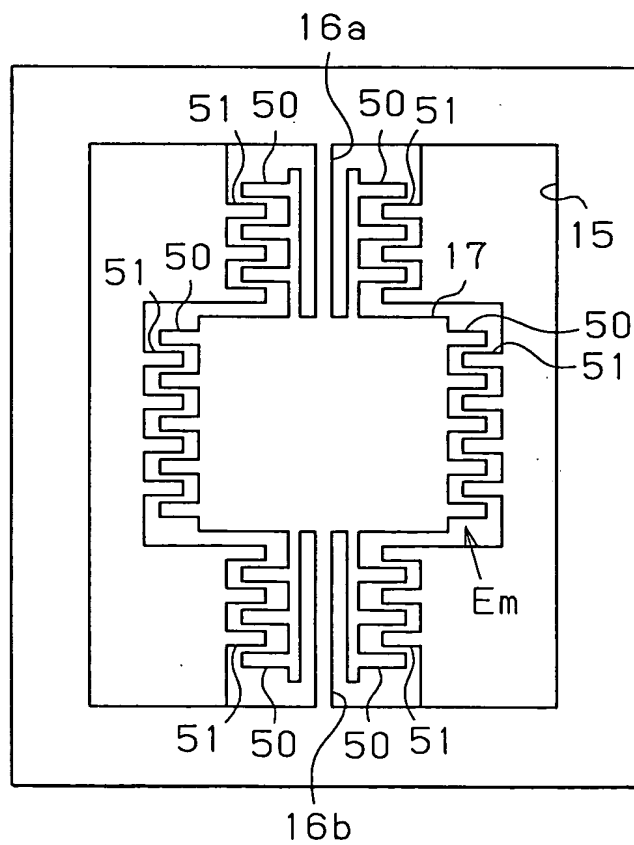


FIG. 25

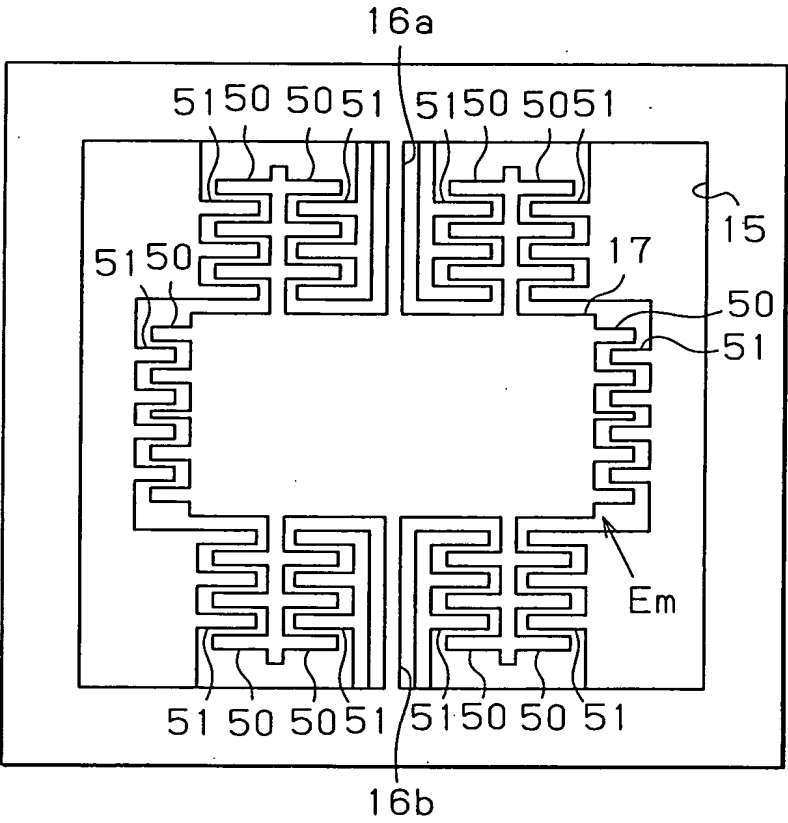


FIG. 26

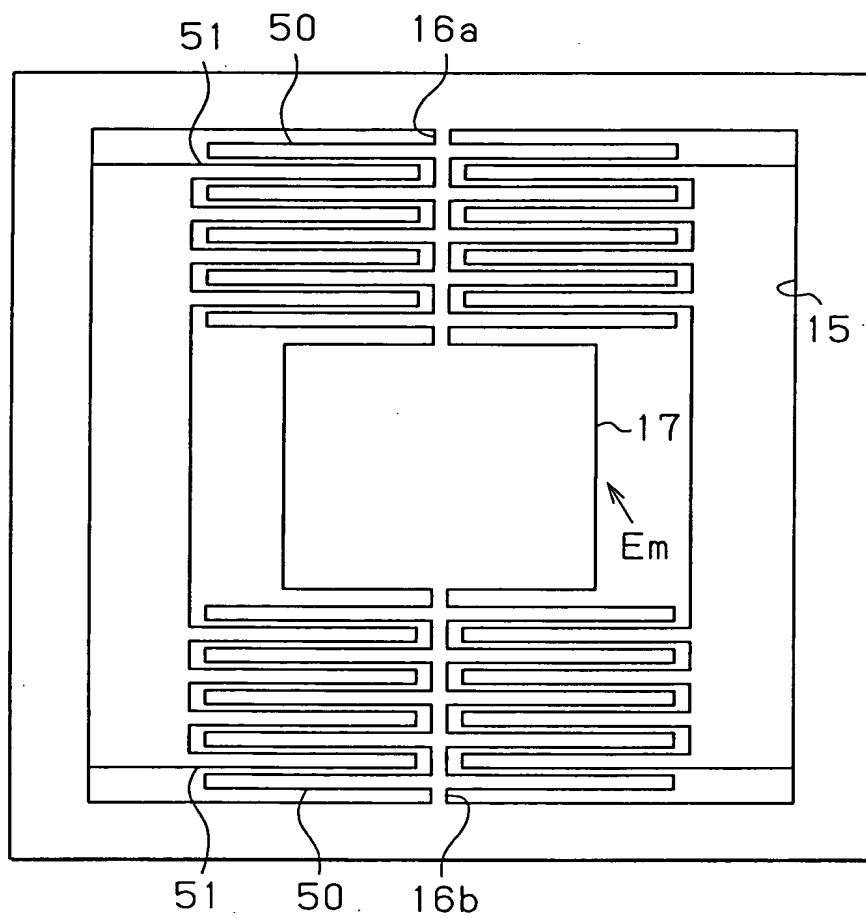
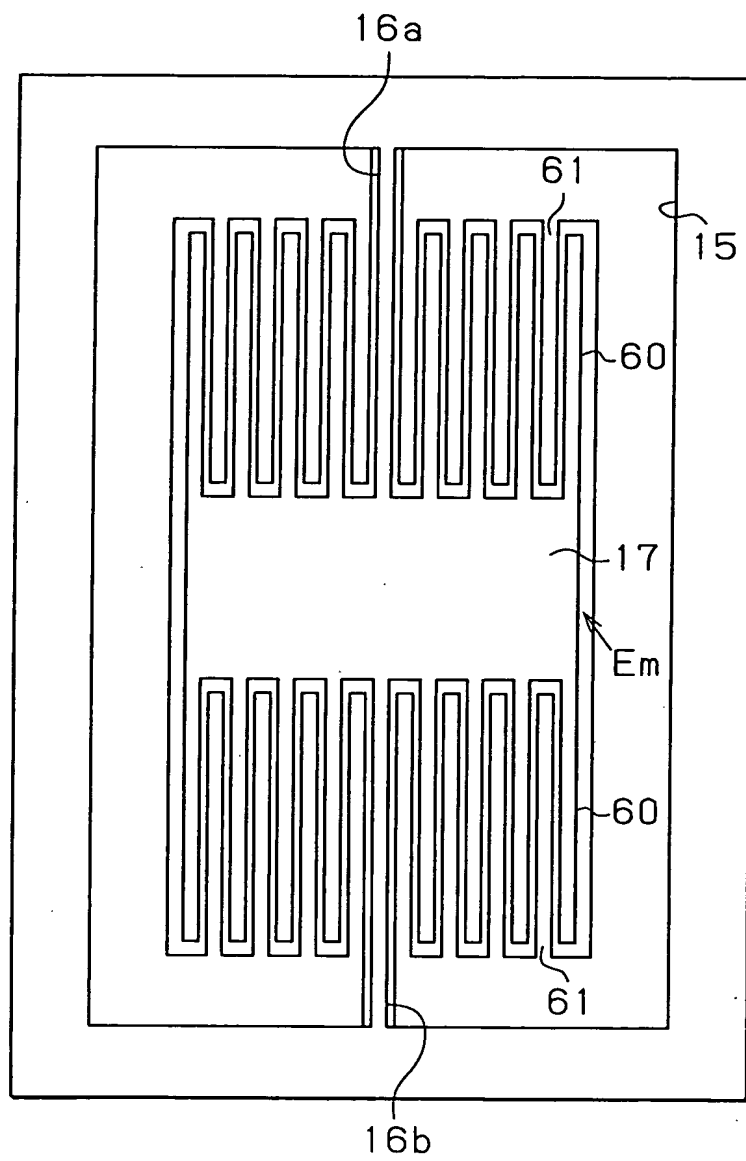
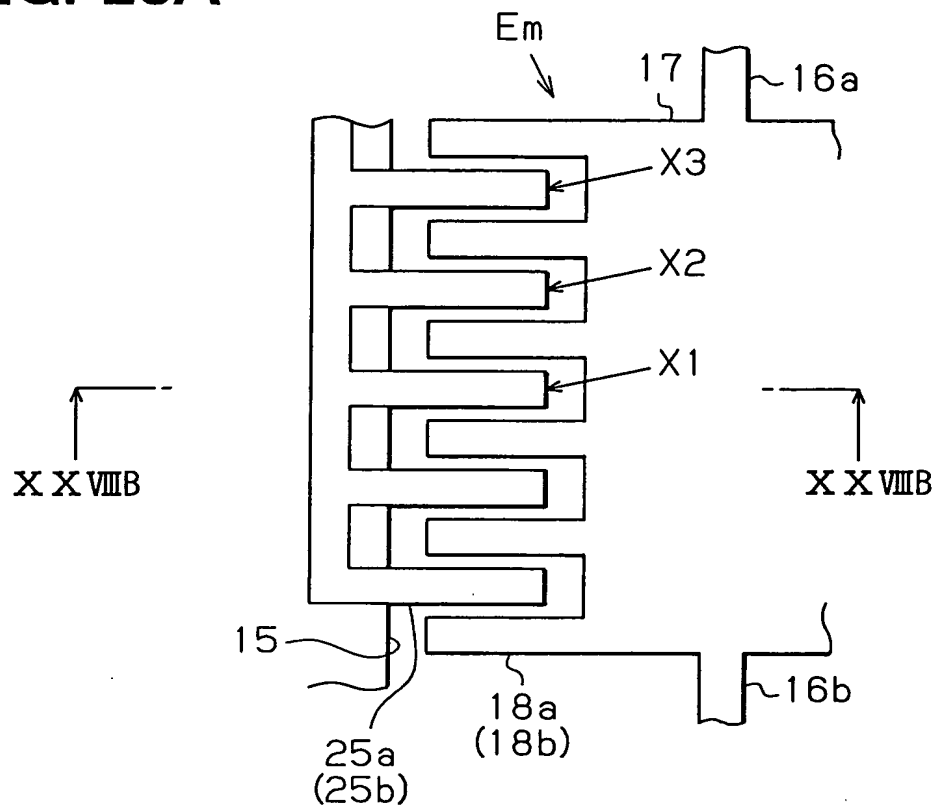


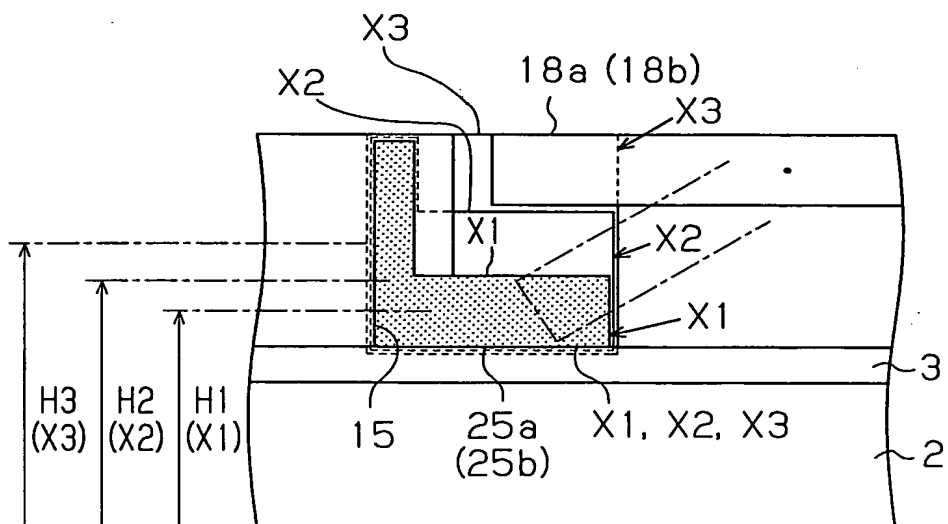
FIG. 27



**FIG. 28A**



**FIG. 28B**



**FIG. 29A**

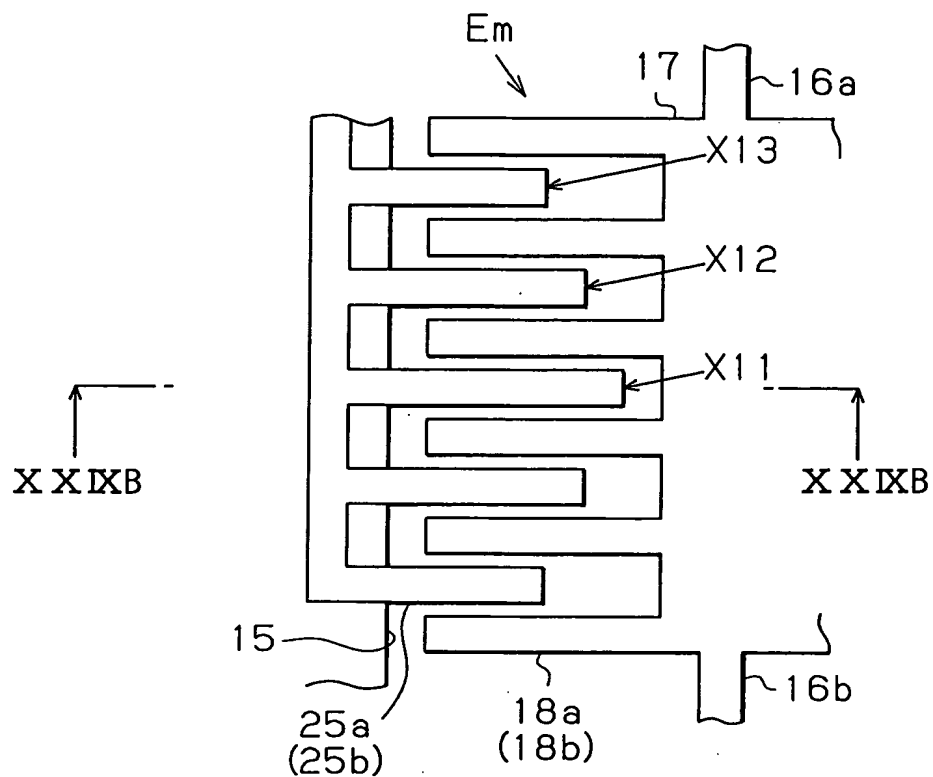
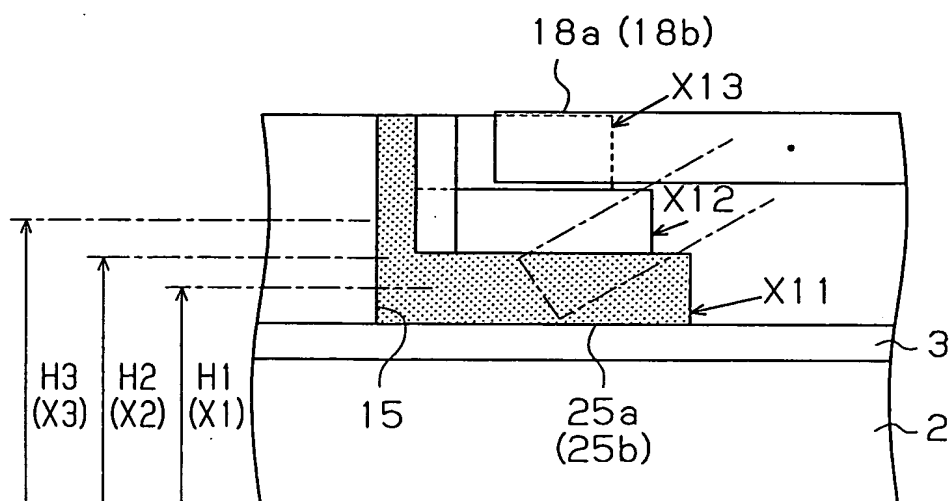
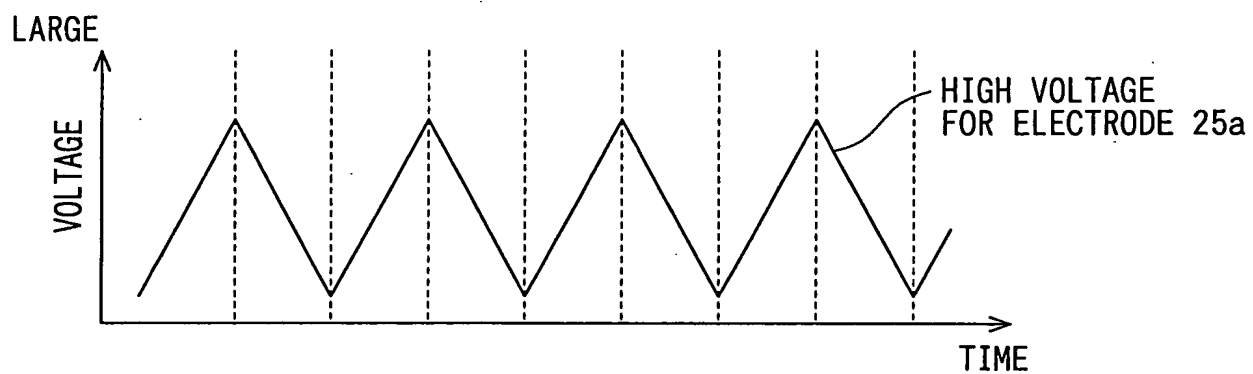


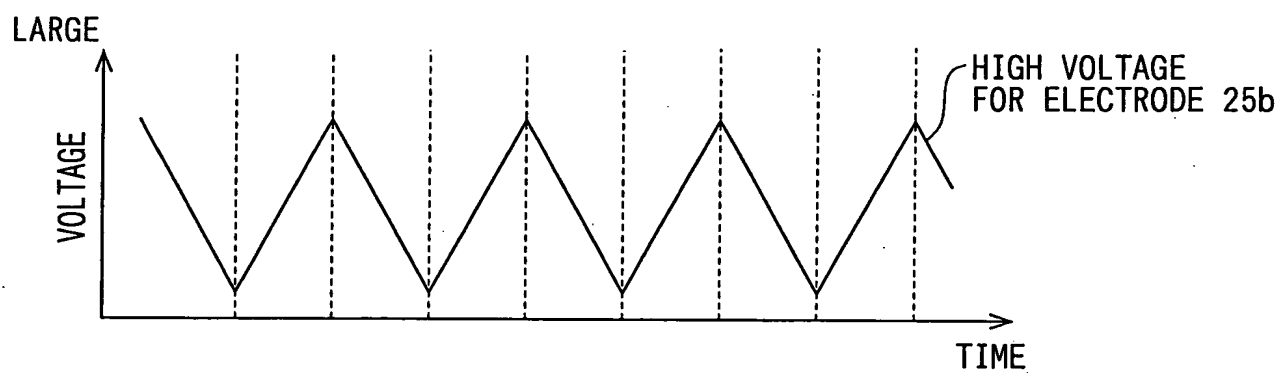
FIG. 29B



# FIG. 30A



# FIG. 30B



# FIG. 31

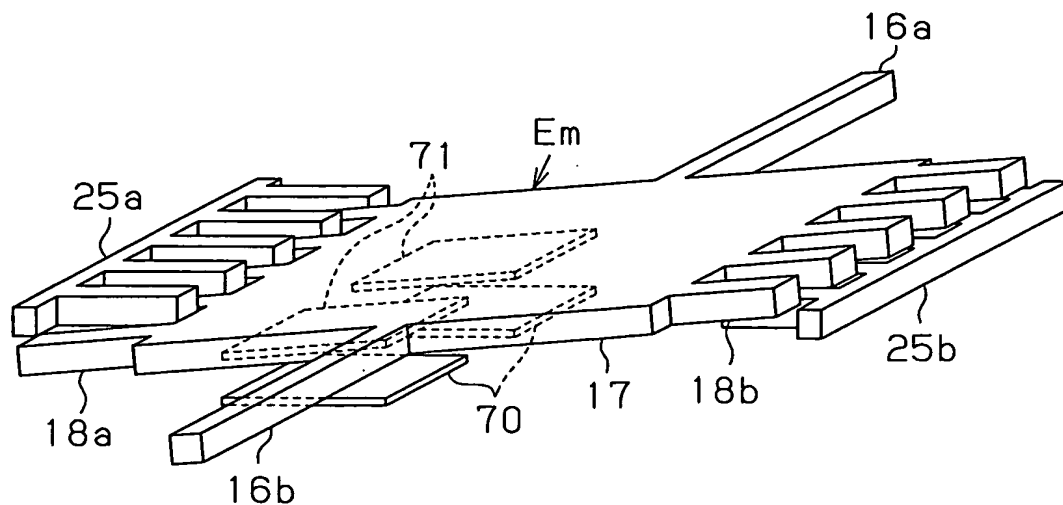


FIG. 32A

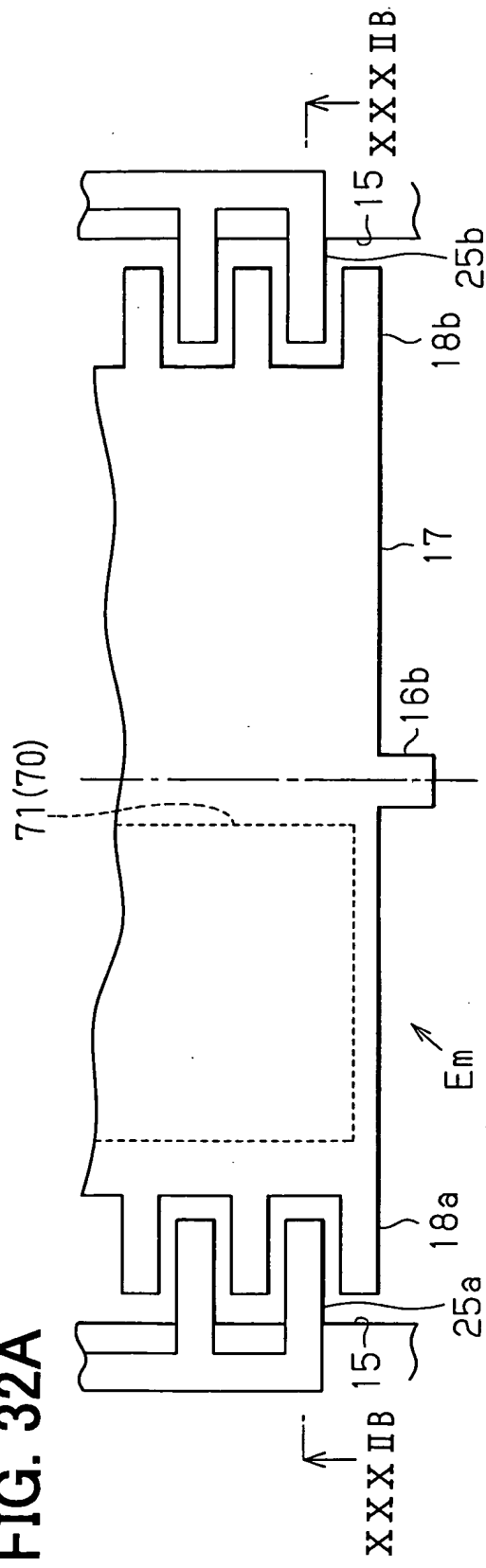


FIG. 32B

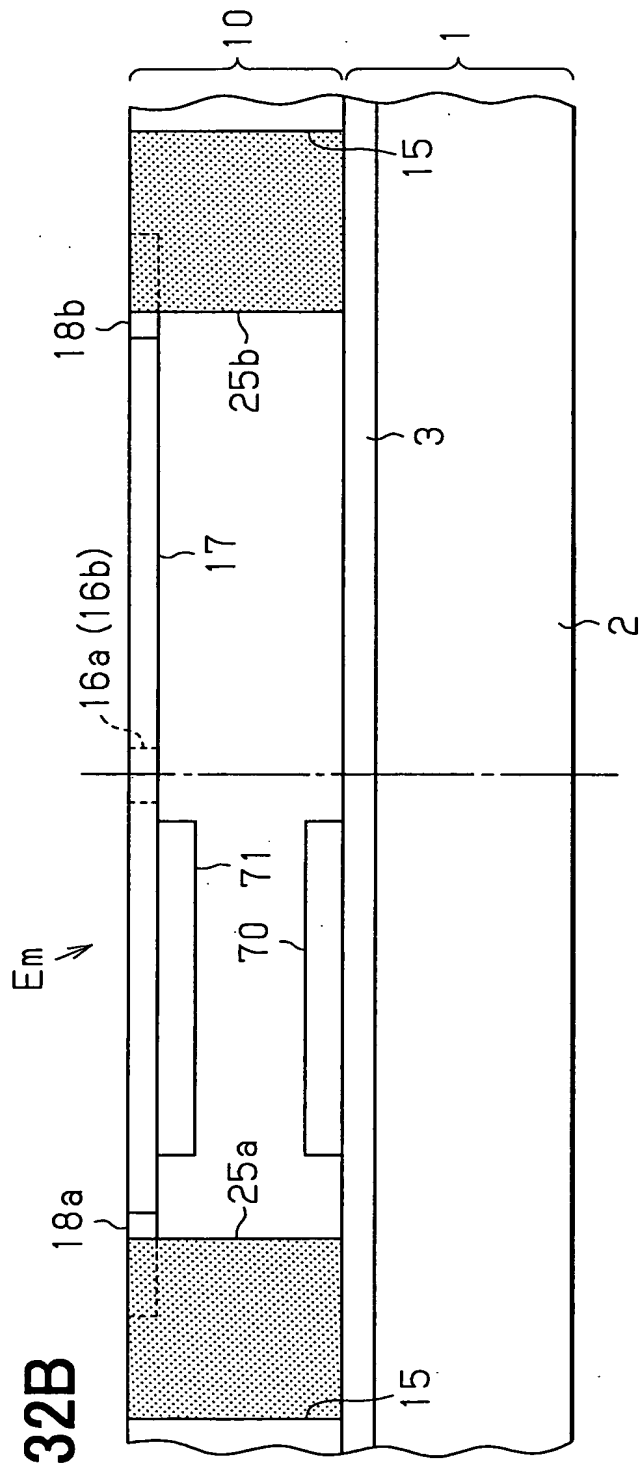
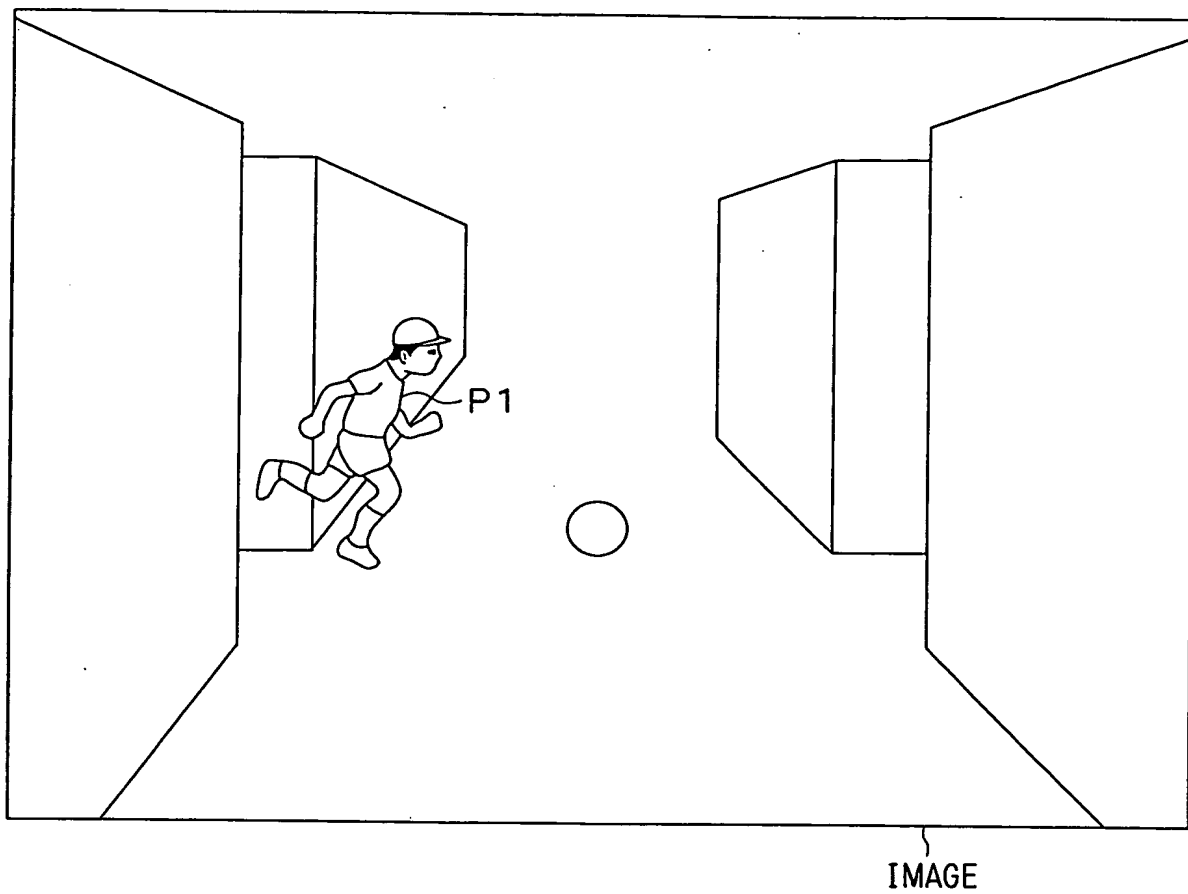
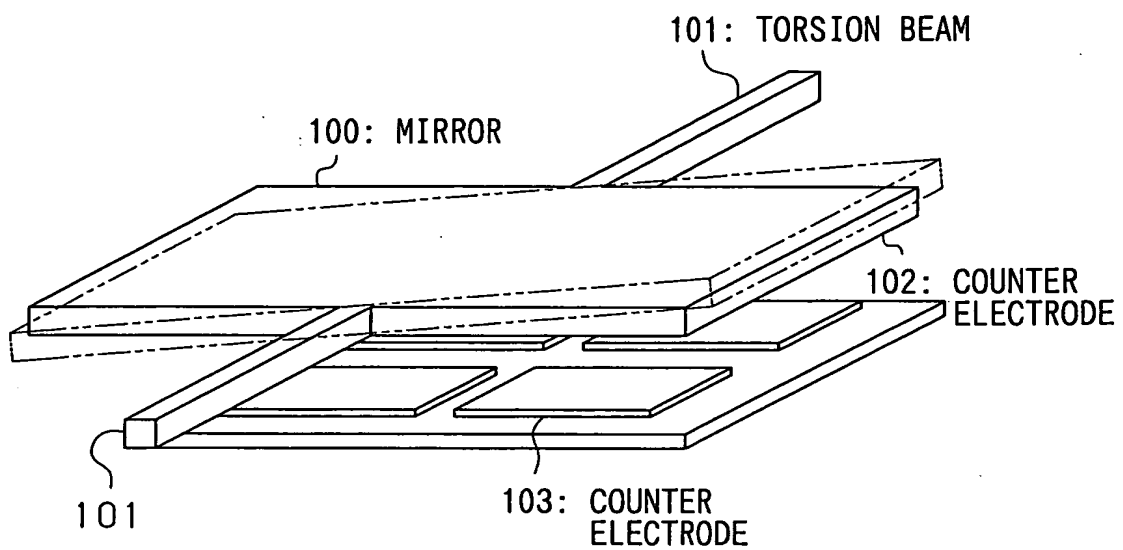


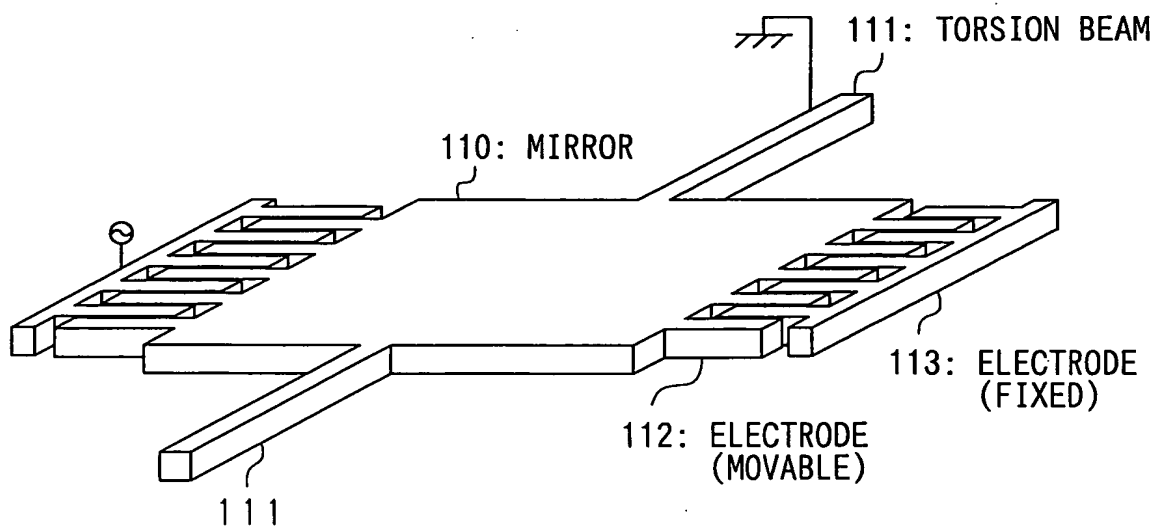
FIG. 33



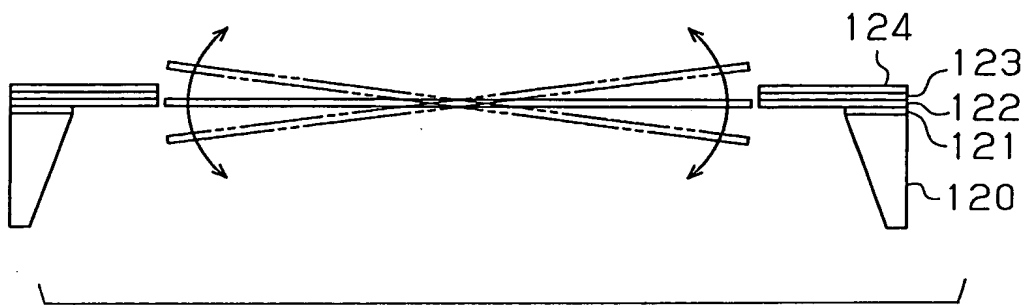
**FIG. 34** RELATED ART



**FIG. 35** RELATED ART



**FIG. 36** RELATED ART



**FIG. 37** RELATED ART

